

What Is Claimed Is:

1. A diode (10) having a press-fit base (11), which includes an axially extending mounting region (12) for a semiconductor chip (15), having a head wire (17), which is provided with a head wire (head) (16) able to be affixed to the semiconductor chip (15), and means for stabilization, which include at least a sleeve (22) and an encapsulating material (23) filling cavities, wherein the head wire (17) includes a stepped wire connection having a region (21), which forms a housing together with the sleeve (22) and the press-fit base (11) as well as the mounting region (12), the cavities of the housing being filled with encapsulating material.
2. The diode as recited in Claim 1, wherein the wire is made of copper and the surface is coated using nickel or a nickel alloy, in particular nickel phosphorus.
3. The diode as recited in one of the preceding claims, wherein the encapsulating material is an epoxy.
4. The diode as recited in one of the preceding claims, wherein only the head (16) of the head wire (17), which is inside the housing, is surrounded by encapsulating material.
5. The diode as recited in one of the preceding claims, wherein the head (16) includes at least two regions having different diameters.
6. The diode as recited in one of the preceding Claims 1 through 4, wherein the head (16) is cone-shaped or bell-shaped.
7. A method for manufacturing a diode as recited in one of the preceding claims, wherein the head wire, the region (21) of the stepped wire connection and the head (16) are produced by extrusion.